



Part Number	AS4C32M16MD1-5BCN / AS4C32M16MD1-5BIN						
Part Weight	116.7mg						
Material	Substances	Vendor	Type	CAS No.	Weight (mg)	%	PPM
Silicon Chip	Silicon (Si)	Elpida	12Mx32 LPDDR	-	5.950	5.10%	50985
Encapsulation (Mold Compound)	Silica, vitreous	KCC	KTMC-5900GL	60676-86-0	60.432	51.78%	517842
	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethyl(1,1'-biphenyl)			85954-11-6	2.108	1.81%	18064
	Phenol, Polymer with 1,4 -bis benzene			26834-02-6	2.108	1.81%	18064
	Carbon Black			1333-86-4	0.422	0.36%	3613
	Others			Trade secret	5.200	4.46%	44559
Substrate	Continuous Filament Fiber Glass	MTG	SU-FBJS-06001W H Rev.0	65997-17-3	3.271	2.80%	28027
	Copper			7440-50-8	9.812	8.41%	84082
	Bismaleimide / Triazine			13676-54-5/25722-66	7.925	6.79%	67913
	Epoxy Resin			26265-08-7	2.768	2.37%	23716
	Inorganic filler			13776-74-4/7631-86-9	0.503	0.43%	4312
	Morpholine derivative(solder resist)			Trade secret	0.503	0.43%	4312
	Nickel			7440-02-0	0.302	0.26%	2587
	Gold			13967-50-5	0.075	0.06%	647
Die Attach (Adhesive)	Acrylic Epoxy Adhesive	KCC	WA-330H-20T	Trade secret	0.546	0.47%	4679
	Acrylic Pressure Sensitive Adhesive			Trade secret	0.294	0.25%	2519
Gold Wire	Gold (Au)	Heesung	0.7mil Au wire	7440-57-5	0.480	0.41%	4113
	Beryllium			7440-41-7	0.000	0.00%	0
	Others			Trade secret	0.000	0.00%	0
Solder Ball	Tin	Duksan	0.45mm (Sn/3Ag/0.5Cu)	7440-31-5	13.510	11.58%	115767
	Silver			7440-22-4	0.420	0.36%	3599
	Copper			7440-50-8	0.070	0.06%	600

